

Product Change Notification - GBNG-11DXBN660

Date: 31 Aug 2017
Product Category: Interface- Serial Peripherals
Notification subject: CCB 2770 Final Notice: Qualification of CuPdAu bond wire and C194 lead frame material in selected products of the 150K wafer technology available in 20L QFN package at NSEB assembly site.
Notification text: **PCN Status:**
 Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire and C194 lead frame material in selected products of the 150K wafer technology available in 20L QFN package at NSEB assembly site.

Pre Change:

Using gold (Au) bond wire and EFTEC-64T lead frame material.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire and C194 lead frame material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	NSEB assembly site	NSEB assembly site
Wire material	Au wire	CuPdAu wire
Die attach material	8600	8600
Molding compound material	G700LTD	G700LTD
Lead frame material	EFTEC-64T	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire and C194 lead frame material at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

September 16, 2017 (1737)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	October 2016				->	August 2017					September 2017			
	41	42	43	44		31	32	33	34	35	36	37	38	39
Initial PCN Issue Date			X											
Qual Report Availability								X						
Final PCN Issue Date								X						
Estimated Implementation Date												X		

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
October 20, 2016: Issued initial notification.
August 16, 2017: Issued final notification. Attached the Qualification Report. Provided estimated first ship date on September 16, 2017
August 31, 2017: Re-issued final notification to update subject from Initial Notice to Final Notice.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_GBNG-11DXBN660_Affected_CPN.pdf](#)
[PCN_GBNG-11DXBN660_Qual Report.pdf](#)
[PCN_GBNG-11DXBN660_Affected_CPN.xlsx](#)

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Affected Catalog Part Number (CPN)

PCN_GBNG-11DXBN660
CATALOG_PART_NBR
MCP23008-E/ML
MCP23008T-E/ML
MCP23S08-E/ML
MCP23S08T-E/ML